



Material Composition Sheet

Product: GS1522-CQRE3
 Package Type: DQFP-128 Pin (66/tray)
 Manufacturer: Gennum Corporation

Date: 06-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		10.50	Al	0.06	0.57	5714
			Si	10.44	99.42	994286
			Sub-total:	10.50	99.99	1000000
Die Attach	CRM 1076DS	3.81	Ag	2.89	75.85	758530
			Epoxy Resin	0.49	12.86	128609
			Epoxy Silane	0.05	1.31	13123
			Phenol Resin	0.11	2.88	28871
			t-Butylphenylglycidil ether	0.27	7.08	70866
Sub-total:	3.81	99.98	999999			
Lead Finish External		31.50	Sn	31.50	100.00	1000000
Sub-total:		31.50		100.00	1000000	
Lead Finish Internal		1.15	Ag	1.15	100.00	1000000
Sub-total:		1.15		100.00	1000000	
Leadframe	OLIN 7025	270.80	Cu	260.51	96.20	962001
			Mg	0.41	0.15	1514
			Ni	8.12	2.99	29985
			Si	1.76	0.64	6499
			Sub-total:	270.80	99.98	999999
Marking Ink	Teca 261	0.10		0.00	0.00	0
Sub-total:		0.10		0.00	0.00	0
Mold Compound	EME G700	1421.81	Carbon Black	7.11	0.50	5001
			Epoxy Resin	113.74	7.99	79997
			Phenol Resin	92.42	6.50	65002
			SiO2	1208.54	85.00	850001
Sub-total:	1421.81	99.99	1000001			
Wires	MGM 7	2.40	Au	2.40	100.00	1000000
			Sub-total:	2.40	100.00	1000000
Total:		1742.07				

GENNUM CORPORATION

Mailing Address: P.O. Box 489, Stn. A, Burlington, Ontario, Canada L7R 3Y3

Shipping Address: 970 Fraser Drive, Burlington, Ontario, Canada L7L 5P5

Tel. +1 (905) 632-2996 Fax. +1 (905) 632-5946

www.gennum.com

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